



Silicon Carbide Dual Schottky Power Rectifier 5A, 1200V

DESCRIPTION

These high current Silicon Carbide Schottkys are rated up to 1200 V and offer very fast switching capabilities with greater efficiency at higher operating temperatures compared to existing ultrafast silicon rectifiers.

Important: For the latest information, visit our website http://www.microsemi.com.

FEATURES

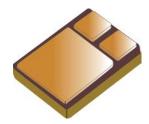
- Low profile ceramic SMD.
- Very lightweight.
- Hermetically sealed.
- High temperature (T_J) +175 °C.
- Zero reverse recovery current.
- Temperature independent switching behavior.
- Very fast switching compared to fast or ultrafast rectifiers.
- Positive V_F temperature coefficient (parallel devices for higher currents).
- RoHS compliant by design.

APPLICATIONS / BENEFITS

- Schottky barrier diode for military, space and other high reliability applications.
- Switching power supplies or other applications requiring extremely fast switching and essentially no switching losses.
- High forward surge capability.
- High reverse voltage capability with very fast switching.
- Inherently radiation hard >100 krads as described in Microsemi MicroNote 050.

MAXIMUM RATINGS @ $T_c = +25$ °C unless otherwise noted

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	$T_{\rm J}$ and $T_{\rm STG}$	-65 to +175	°C
Thermal Resistance, Junction-to-Case	R _θ JC	1.7	°C/W
Working Peak Reverse Voltage	V _{RWM}	1200	V
Non-Repetitive Peak Inverse Voltage	V _{RSM}	1200	V
DC Blocking Voltage	V _{DC}	1200	V
Average DC Output Current @ 25°C	lo	5	Α
Non-Repetitive Sinusoidal Surge Current	I _{FSM}	30	Α
@ tp = 8.3 ms, half sinewave, $I_0 = 0$; $V_{RM} = 0$			



U3 (SMD-5) Package

Also available in:

Dual TO-257 package (leaded)

MSICSN05120CC, CA, D

TO-257 package (leaded) MSiCSN05120

TO-257 tabless package (leaded)

> U4 package (surface mount) MSiCSS05120

MSC – Lawrence

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MSC – Ireland

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Website:

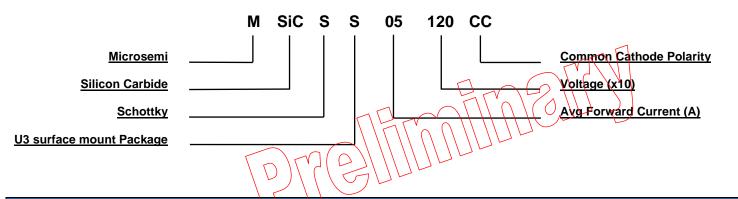
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MECHANICAL and PACKAGING

- CASE: Ceramic and gold-over-nickel plated steel.
- TERMINALS: Gold-over-nickel plated tungsten/copper.
- MARKING: Alpha numeric.
- POLARITY: See <u>schematic</u> on last page.
- WEIGHT: Approximately 0.9 grams.
- See <u>package dimensions</u> on last page.

PART NOMENCLATURE



Symbol	Definition					
CJ	Junction Capacitance: The junction capacitance in pF at a specified frequency (typically 1 MHz) and specified voltage.					
١ _F	Forward Current: The forward current dc value, no alternating component.					
I _R	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.					
TJ	Junction Temperature: The temperature of a semiconductor junction.					
V _F	Forward Voltage: The forward voltage the device will exhibit at a specified current (typically shown as maximum value).					
V _R	Reverse Voltage: The reverse voltage dc value, no alternating component.					



Parameters / Test Conditions	Symbol	Min.	Max.	Тур.	Unit
Forward Voltage* $I_F = 1 A, T_J = 25 °C$ $I_F = 2.5 A, T_J = 25 °C$ $I_F = 5.0 A, T_J = 25 °C$	V _F		1.2 1.6 1.8		V
Reverse Current $V_R = 1200 V, T_J = 25 °C$ $V_R = 1200 V, T_J = 175 °C$	I _R		50 100		μA
Junction Capacitance $V_R = 0 V$ f = 1 MHz	CJ			500	pF

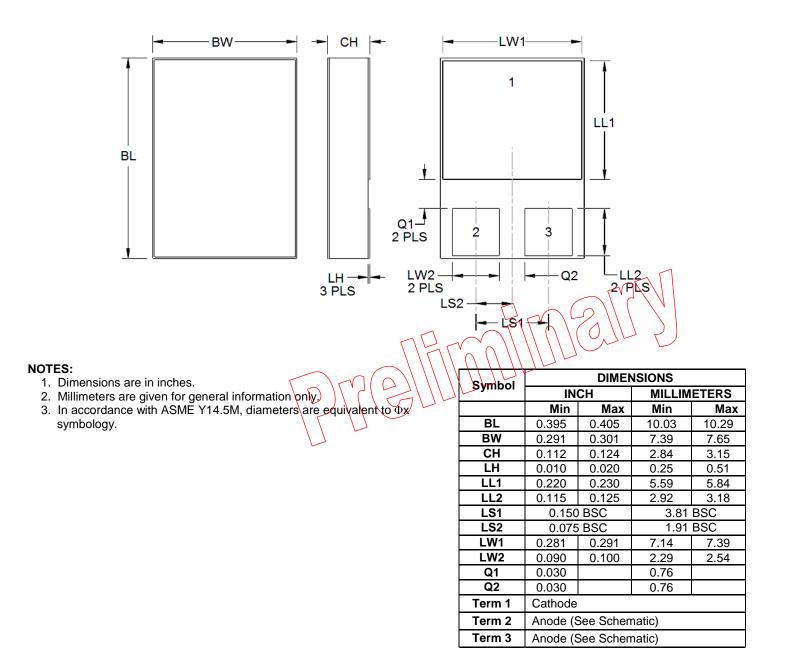
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ELECTRICAL CHARACTERISTICS @ T_A = +25 °C unless otherwise noted

* Pulse test: Pulse width 300 µsec, duty cycle 2%.



PACKAGE DIMENSIONS



SCHEMATIC

